

HSF

NOTES:

Rated Current: 5.0AMP.(20°C,2*2P-2*15P)
 3.0AMP.(20°C,2*16P-2*40P) $\triangle A3$

Contact Resistance: 20mΩ Max.
 Withstand Voltage: 1000V AC/DC
 Insulation Resistance: 1000MΩ Min.
 Operation Temperature: -40°C to +125°C(Gold Plating)
 -40°C to +105°C(Tin Plating)

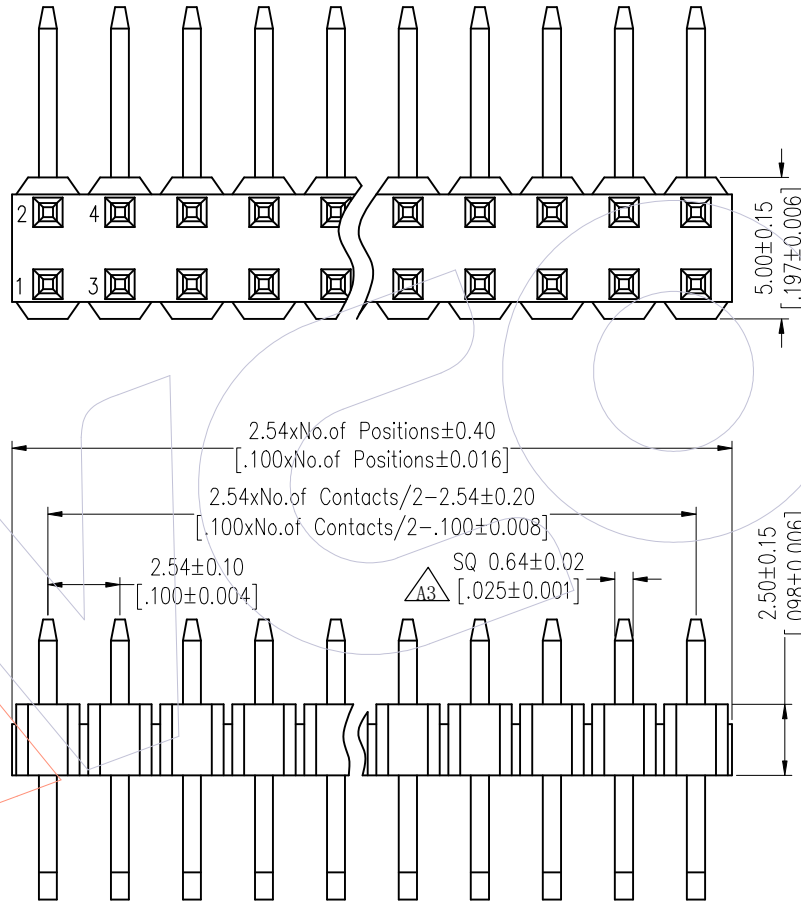
Contact Material: Copper Alloy $\triangle A3$
 Contact Plating: Au or Sn Over 30u" Min Ni
 Insulator Material: PA9T+G.F UL94V-0 BK $\triangle A3$

1125-1 2 XX XX R XXX C X XX $\triangle A3$

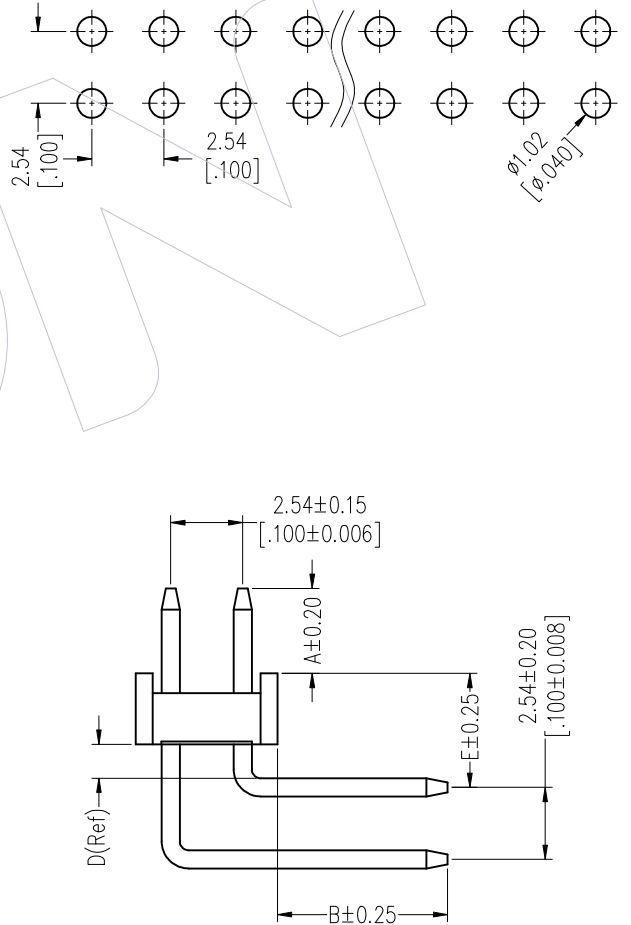
Plastic Layer
 Plastic Row
 No. of Pins Per Row: 02-40
 Contact Plating
 G0=Gold Flash
 G3=10u"Au, BG3=8u"PdNi+2u"Au
 G4=15u"Au, BG4=13u"PdNi+2u"Au
 G5=30u"Au, BG5=28u"PdNi+2u"Au
 S0=Gold Flash/Tin
 S3=10u"Au/Sn, P3=8u"PdNi+2u"Au/Sn
 S4=15u"Au/Sn, P4=13u"PdNi+2u"Au/Sn
 S5=30u"Au/Sn, P5=28u"PdNi+2u"Au/Sn
 SN=Bright Tin
 SM=Matte Tin $\triangle A3$

Series No. 01-99
 Packing 0=PE Bag
 Insulator Material C=PA9T
 Pin Length L(See Table)
 Type: R/R/A

Item	Pin Length Short/Long	A	D	E	B	Mating
Standard	11.3/16.3	3.0	1.20	4.02	3.5	2135/2150T/2157
	11.8/16.8				4.0	2145/2150
	12.8/17.8				5.0	2168T/2171T
	13.5/18.5				5.84	2171/2185X
Standard	10.3/15.3	2.0 (THR)	1.20	4.02	3.5	2135/2150T/2157
	10.8/15.8				4.0	2145/2150
	11.8/16.8				5.0	2168T/2171T
	12.5/17.5				5.84	2171/2185X
Alternate						



Recommended P.C.B Layout (Top Side)
 (PCB BOARD TOLERANCE ±0.05)
 (PCB Thickness: T=1.60mm)



REV	DATE	MODIFICATION DESCRIPTION	CHANGE	DIM	TOL	APPROVE	DATE	PROJ.
A3	2025/03/11	Standardization Drawing	CP			DRAW	2025/03/11	
A2	2018/06/02	Cancel PBT & Modify P/N	Surong Xu	x.X	±0.40	CP		
A1	2018/01/22	Modify P/N	Ruipeng	x.XX	±0.25	CHECK	2025/03/11	
A0	2012/05/28	NEW	William Chen	x.XXX	±0.15	TANG		
				Angle	± 3°	APPROVE	2025/03/11	
						Steven Zhao		

PART NO.	1125-12XXXXRXXX $\triangle A1 \triangle A2$
TITLE:	PH2.54 DUAL ROW 90° PLANE BENDING H=2.5
Customer NO.	

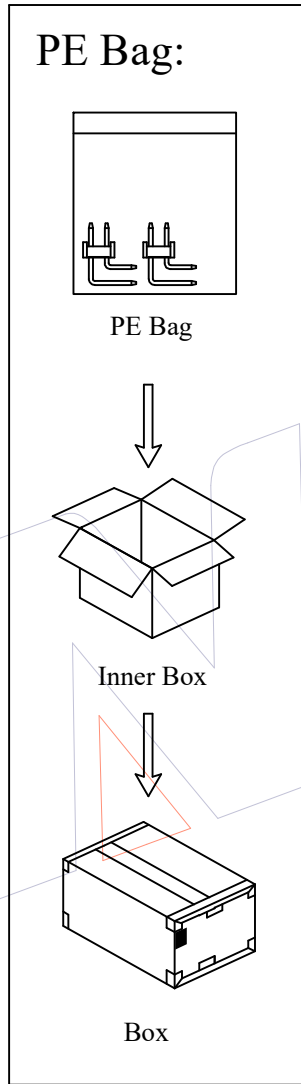
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Packing:



Packaging Quantity Refers To The Following Table

PINS /Row	Q' ty/Bag (10.0<L≤16.0)	PINS /Row	Q' ty/Bag (10.0<L≤16.0)
2	1000	22	100
3	1000	23	100
4	300	24	100
5	500	25	100
6	500	26	100
7	300	27	100
8	300	28	100
9	200	29	50
10	200	30	50
11	200	31	50
12	200	32	50
13	200	33	50
14	200	34	50
15	200	35	50
16	200	36	50
17	200	37	50
18	200	38	50
19	100	39	50
20	100	40	50
21	100		

A3	2025/03/11	Standardization Drawing	CP	OPERATION	DRAW	DATE	SCALE	Fit	PART NO. 1125-12XXXXRXXX \triangle_{A1} \triangle_{A2}
A2	2018/06/02	Cancel PBT & Modify P/N	Surong Xu	x.X ±0.40	CP	2025/03/11	UNIT	mm	
A1	2018/01/22	Modify P/N	Ruipeng	x.xx ±0.25	CHECK	DATE	SIZE	A4	TITLE: PH2.54 DUAL ROW 90° PLANE BENDING H=2.5
A0	2012/05/28	NEW	William Chen	x.xxx ±0.15	TANG	2025/03/11	SHEET	2/2	
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	Angle DIM	± 3° TOL	APPROVE Steven Zhao	DATE	PROJ.	Customer NO.

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